DISCONTINUED

ZXMN3F318DN8

30V SO8 Asymmetrical dual N-channel enhancement mode MOSFET

Summary

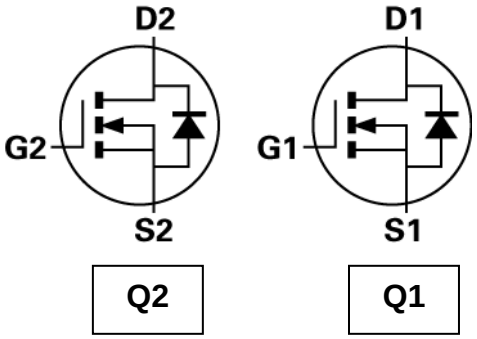
Device	$V_{(BR)DSS}$	Q_G (nC)	$R_{DS(on)}$ (Ω)	I_D (A)
Q1	30	12.9	0.024 @ V_{GS}= 10V	7.3
			0.039 @ V_{GS}= 4.5V	5.7
Q2	30	9	0.035 @ V_{GS}= 10V	6
			0.055 @ V_{GS}= 4.5V	4.8

Description

This new generation dual Trench MOSFET from Zetex features low on-resistance achievable with low (4.5V) gate drive.

Features

- Low on-resistance
- 4.5V gate drive capability
- Low profile SOIC package

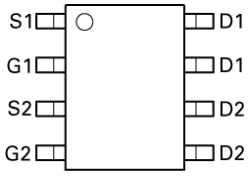


Applications

- DC-DC Converters
- SMPS
- Load switching
- Motor control
- Backlighting

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN3F318DN8TA	7	12	500



Pinout – top view

Device marking

ZXMN

3F318

ABSOLUTE MAXIMUM RATINGS

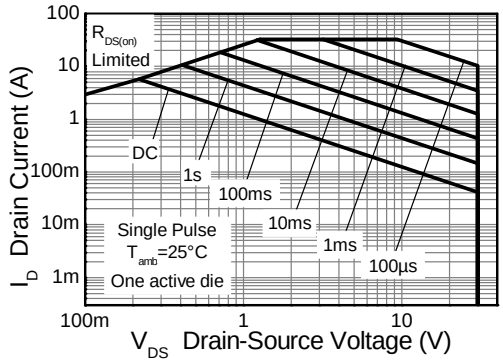
PARAMETER	SYMBOL	LIMIT Q1	LIMIT Q2	UNIT
Drain-Source Voltage	V_{DSS}	30	30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current V_{GS}=10V; T_A=25°C (b)	I_D	7.3	6	A
V_{GS}=10V; T_A=70°C (b)		5.9	4.8	
V_{GS}=10V; T_A=25°C (a)		5.7	4.6	
Pulsed Drain Current (c)	I_{DM}	33	25	A
Continuous Source Current (Body Diode) (b)	I_S	3.5	3.3	A
Pulsed Source Current (Body Diode) (c)	I_{SM}	33	25	A
Power Dissipation at T_A =25°C (a) (d)	P_D	1.25		W
Linear Derating Factor		10		mW/°C
Power Dissipation at T_A =25°C (a) (e)	P_D	1.8		W
Linear Derating Factor		14		mW/°C
Power Dissipation at T_A =25°C (b) (d)	P_D	2.1		W
Linear Derating Factor		17		mW/°C
Operating and Storage Temperature Range	T_j, T_{stg}	-55 to +150		°C

THERMAL RESISTANCE

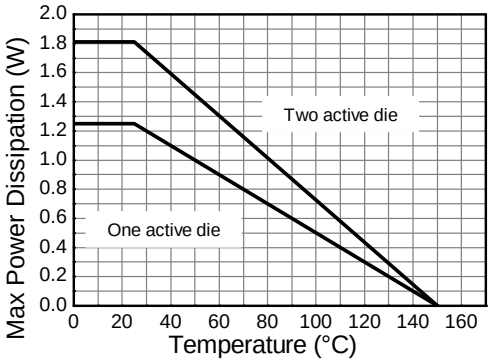
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a) (d)	$R_{\theta JA}$	100	°C/W
Junction to Ambient (a) (e)	$R_{\theta JA}$	70	°C/W
Junction to Ambient (b) (d)	$R_{\theta JA}$	60	°C/W
Junction to Lead (f)	$R_{\theta JL}$	53	°C/W

NOTES
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
(b) For a device surface mounted on FR4 PCB measured at t ≤ 10 sec.
(c) Repetitive rating - 25mm x 25mm FR4 PCB, D=0.02, pulse width 300us – pulse width limited by maximum junction temperature.
(d) For a dual device with one active die.
(e) For a device with two active die running at equal power.
(f) Thermal resistance from junction to solder-point (at the end of the drain lead).

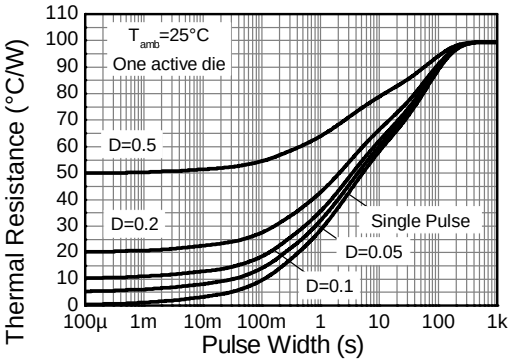
Q1 Thermal Characteristics



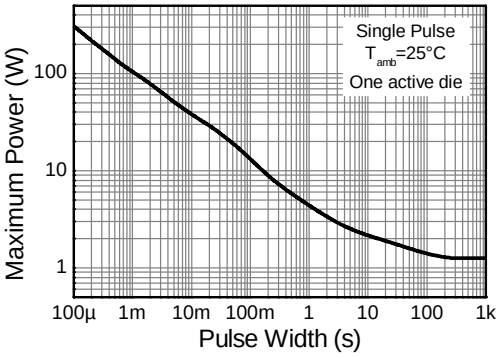
Safe Operating Area



Derating Curve



Transient Thermal Impedance



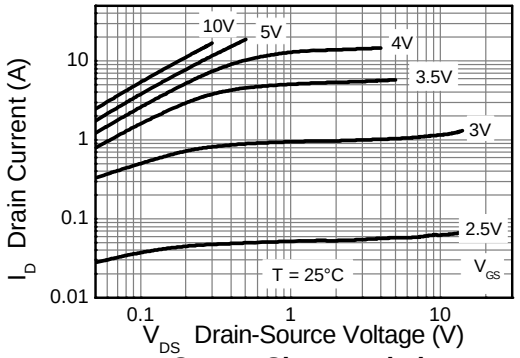
Pulse Power Dissipation

Q1 ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

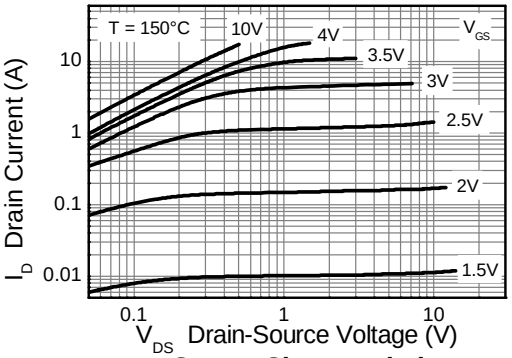
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30			V	I_D= 250μA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			0.5	μA	V_{DS}= 30V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			100	nA	V_{GS}=±20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0		3.0	V	I_D= 250μA, V_{DS}=V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.024	Ω	V_{GS}= 10V, I_D= 7.0A
				0.039	Ω	V_{GS}= 4.5V, I_D = 6.0A
Forward Transconductance (1) (3)	g_{fs}		16.5		S	V_{DS}= 15V, I_D= 7A
DYNAMIC (3)						
Input Capacitance	C_{iss}		608		pF	V_{DS}= 15V, V_{GS}=0V f=1MHz
Output Capacitance	C_{oss}		132		pF	
Reverse Transfer Capacitance	C_{rss}		71		pF	
SWITCHING (2) (3)						
Turn-On-Delay Time	$t_{d(on)}$		2.9		ns	V_{DD}= 15V, I_D= 1A R_G≅6.0Ω, V_{GS}= 10V
Rise Time	t_r		3.3		ns	
Turn-Off Delay Time	$t_{d(off)}$		16		ns	
Fall Time	t_f		8		ns	
Total Gate Charge	Q_g		12.9		nC	V_{DS}= 15V, V_{GS}= 10V I_D= 7A
Gate-Source Charge	Q_{gs}		2.5		nC	
Gate Drain Charge	Q_{gd}		2.52		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		0.82	1.2	V	T_j=25°C, I_S= 1.7A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		12		ns	T_j=25°C, I_S= 2.2A, di/dt=100A/μs
Reverse Recovery Charge (3)	Q_{rr}		4.8		nC	

(1) Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
(2) Switching characteristics are independent of operating junction temperature.
(3) For design aid only, not subject to production testing.

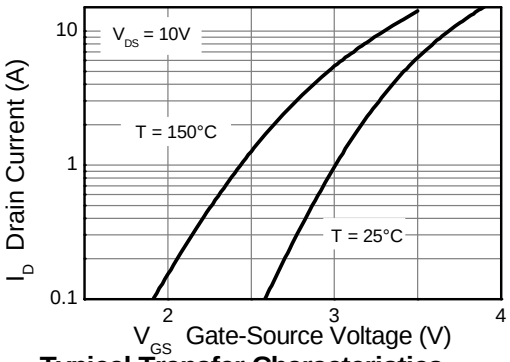
Q1 Typical Characteristics



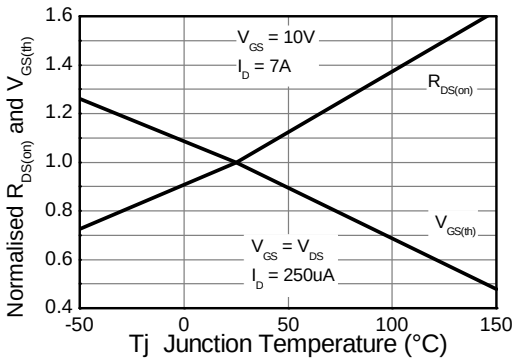
Output Characteristics



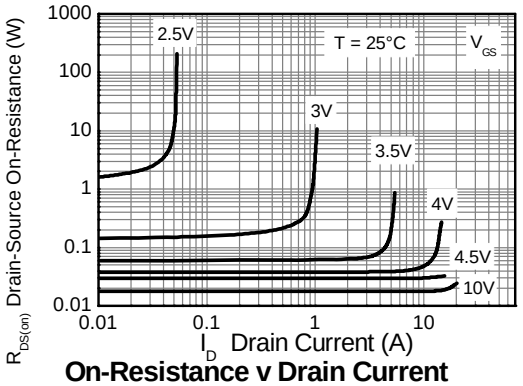
Output Characteristics



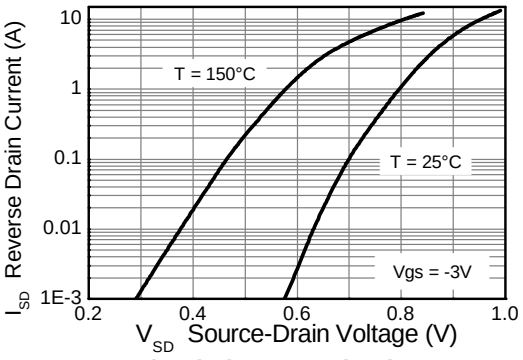
Typical Transfer Characteristics



Normalised Curves v Temperature

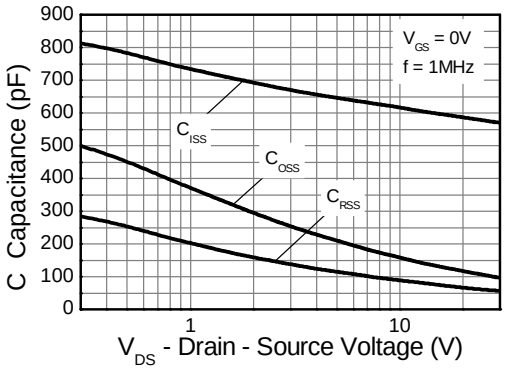


On-Resistance v Drain Current

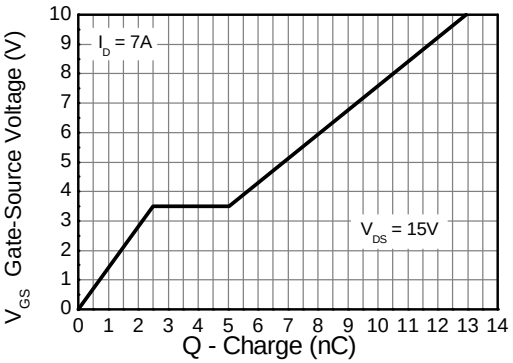


Source-Drain Diode Forward Voltage

Q1 Typical Characteristics

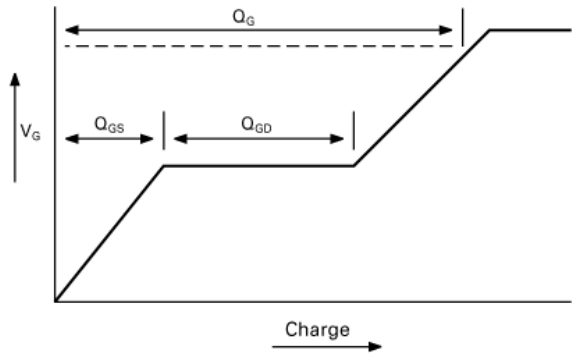


Capacitance v Drain-Source Voltage

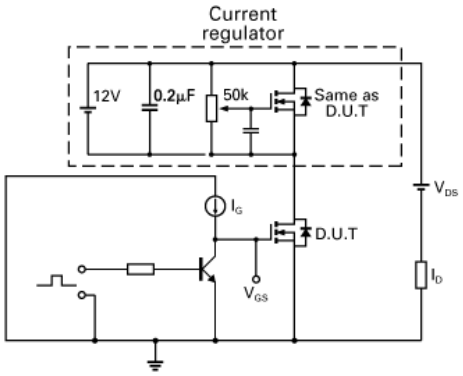


Gate-Source Voltage v Gate Charge

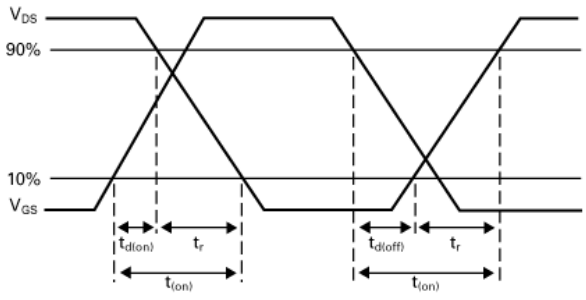
Test Circuits



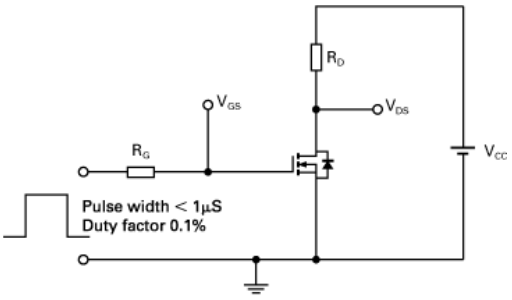
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms



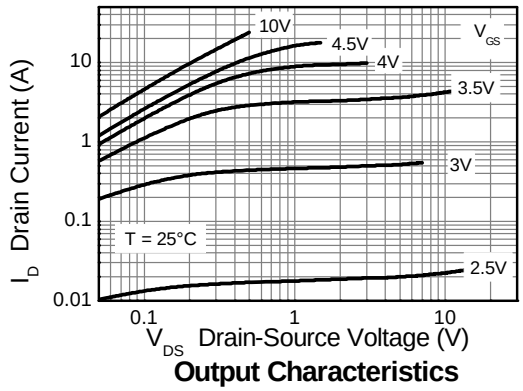
Switching time test circuit

Q2 ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

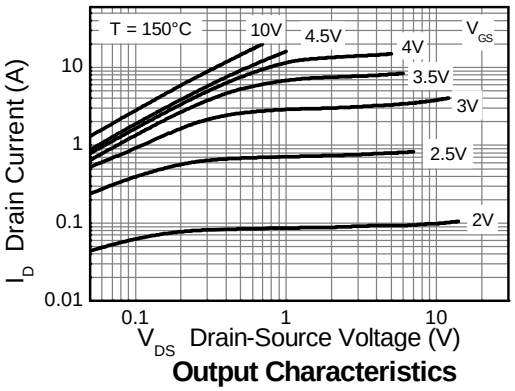
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30			V	I_D= 250μA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			0.5	μA	V_{DS}= 30V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			100	nA	V_{GS}=±20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0		3.0	V	I_D= 250μA, V_{DS}=V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.035	Ω	V_{GS}= 10V, I_D= 5.0A
				0.055	Ω	V_{GS}= 4.5V, I_D = 4A
Forward Transconductance (1) (3)	g_{fs}		11.8		S	V_{DS}= 15V, I_D= 5A
DYNAMIC (3)						
Input Capacitance	C_{iss}		430		pF	V_{DS}= 15V, V_{GS}=0V f=1MHz
Output Capacitance	C_{oss}		101		pF	
Reverse Transfer Capacitance	C_{rss}		56		pF	
SWITCHING (2) (3)						
Turn-On-Delay Time	$t_{d(on)}$		2.5		ns	V_{DD}= 15V, I_D= 1A R_G≅6.0Ω, V_{GS}= 10V
Rise Time	t_r		3.3		ns	
Turn-Off Delay Time	$t_{d(off)}$		11.5		ns	
Fall Time	t_f		6.3		ns	
Total Gate Charge	Q_g		9		nC	V_{DS}= 15V, V_{GS}= 10V I_D= 5A
Gate-Source Charge	Q_{gs}		1.7		nC	
Gate Drain Charge	Q_{gd}		2		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		0.82	1.2	V	T_j=25°C, I_S= 1.7A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		12		ns	T_j=25°C, I_S= 2.1A, di/dt=100A/μs
Reverse Recovery Charge (3)	Q_{rr}		4.9		nC	

1 Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
2 Switching characteristics are independent of operating junction temperature.
3 For design aid only, not subject to production testing.

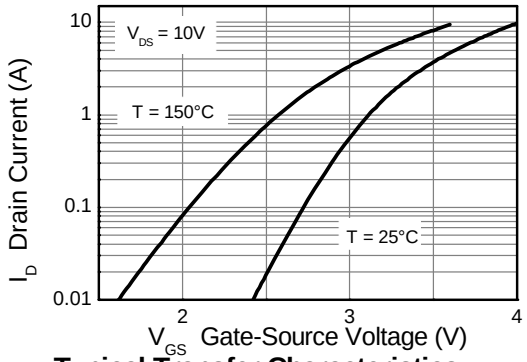
Q2 Typical Characteristics



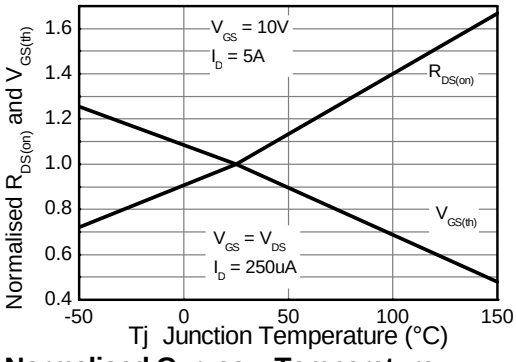
Output Characteristics



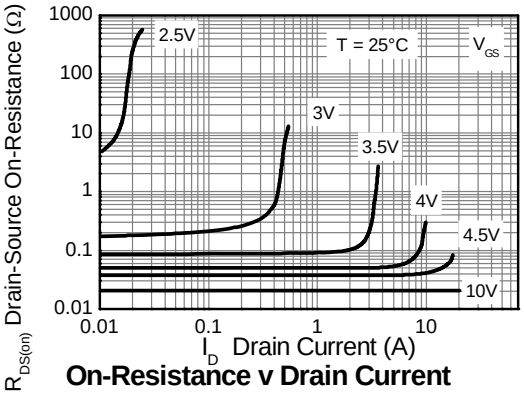
Output Characteristics



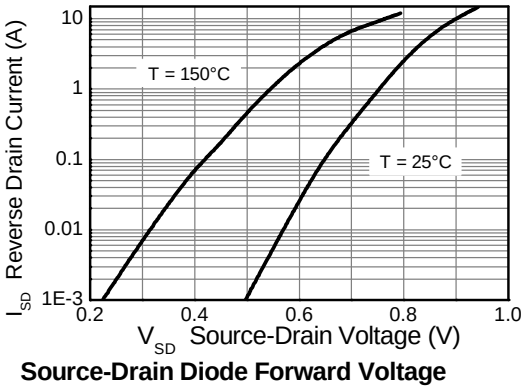
Typical Transfer Characteristics



Normalised Curves v Temperature

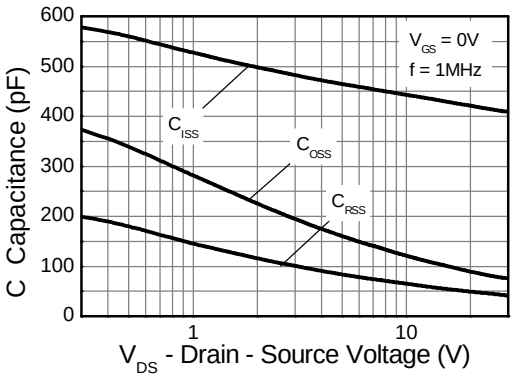


On-Resistance v Drain Current

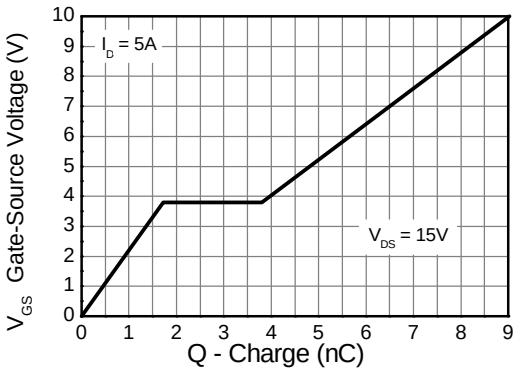


Source-Drain Diode Forward Voltage

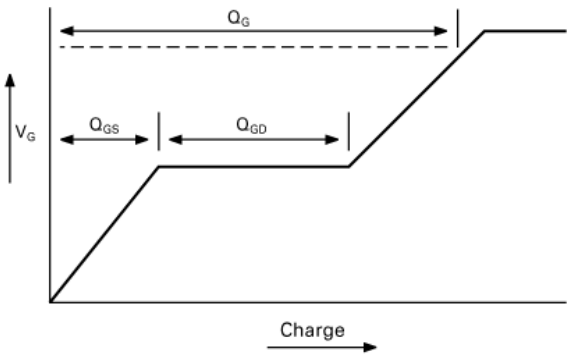
Q2 Typical Characteristics



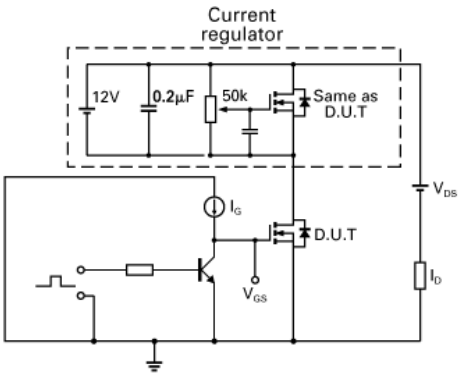
Capacitance v Drain-Source Voltage



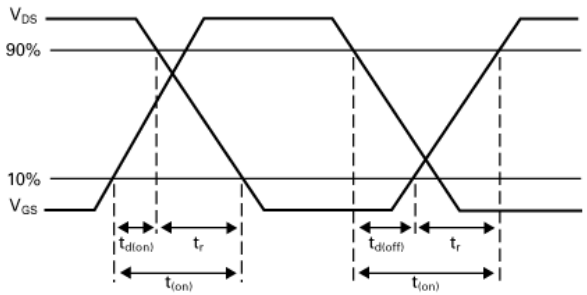
Gate-Source Voltage v Gate Charge



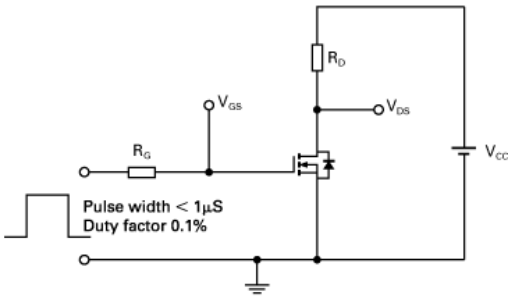
Basic gate charge waveform



Gate charge test circuit



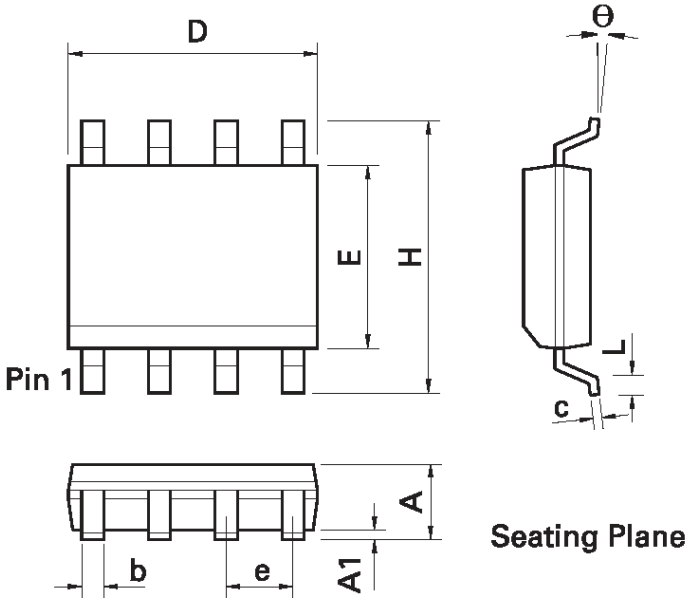
Switching time waveforms



Switching time test circuit

Packaging details – SO8

Package outline



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.053	0.069	1.35	1.75	e	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25
H	0.228	0.244	5.80	6.20	Θ	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Note: Controlling dimensions are in inches. Approximate dimensions are provided in millimeters

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or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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ESD (Electrostatic discharge)
Semiconductor devices are susceptible to damage by ESD. Suitable precautions should be taken when handling and transporting devices. The possible damage to devices depends on the circumstances of the handling and transporting, and the nature of the device. The extent of damage can vary from immediate functional or parametric malfunction to degradation of function or performance in use over time. Devices suspected of being affected should be replaced.

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All Diodes Zetex components are compliant with the RoHS directive, and through this it is supporting its customers in their compliance with WEEE and ELV directives.

Product status key:

"Preview"	Future device intended for production at some point. Samples may be available
"Active"	Product status recommended for new designs
"Last time buy (LTB)"	Device will be discontinued and last time buy period and delivery is in effect
"Not recommended for new designs"	Device is still in production to support existing designs and production
"Obsolete"	Production has been discontinued

Datasheet status key:

"Draft version"	This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.
"Provisional version"	This term denotes a pre-release datasheet. It provides a clear indication of anticipated performance. However, changes to the test conditions and specifications may occur, at any time and without notice.
"Issue"	This term denotes an issued datasheet containing finalized specifications. However, changes to specifications may occur, at any time and without notice.

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